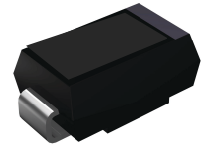


## Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low profile package
- Built-in strain relief, ideal for automated placement
- Glass passivated chip junction



DO-214AB(SMC)

## Mechanical Data

- Case: JEDEC DO-214AB (SMC) molded plastic body over glass passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Polarity: Color band denotes cathode end



## Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	SN6A	SN6B	SN6D	SN6G	SN6J	SN6K	SN6M	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T <sub>L</sub> (See Fig.1)	I <sub>F(AV)</sub>	6.0							A
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	I <sub>FSM</sub>	320							A
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	- 55 to + 150							°C

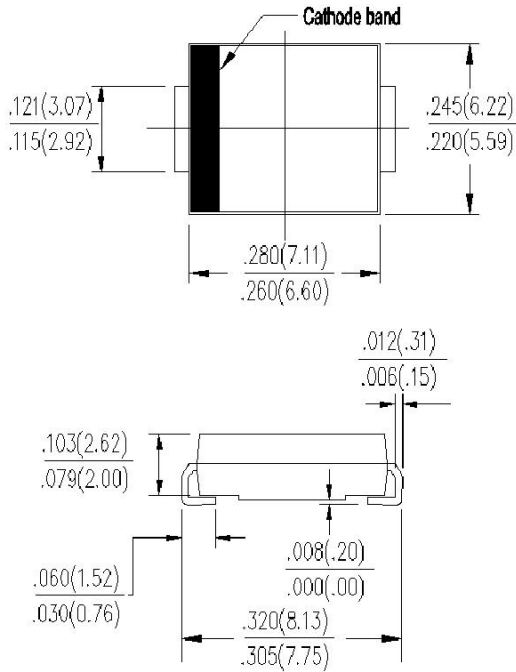
## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	SN6A	SN6B	SN6D	SN6G	SN6J	SN6K	SN6M	Unit
Maximum Instantaneous Forward Voltage	6A	V <sub>F</sub>	1.1							V
Maximum DC Reverse Current at rated DC Blocking Voltage	T <sub>A</sub> =25°C	I <sub>R</sub>	5							μA
	T <sub>A</sub> =100°C		150							
Typical Thermal Resistance <sup>1)</sup>	Junction to Ambient	R <sub>θJA</sub>	30							°C/W
Typical Junction Capacitance	4.0 V, 1 MHz	C <sub>J</sub>	150							pF

Note:1)The thermal resistance from junction to ambient,case or lead,mounted on P.C.B with 30×30mm copper pads

## Package Outline Dimensions

DO-214AB(SMC)



## Mounting Pad Layout

